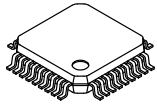
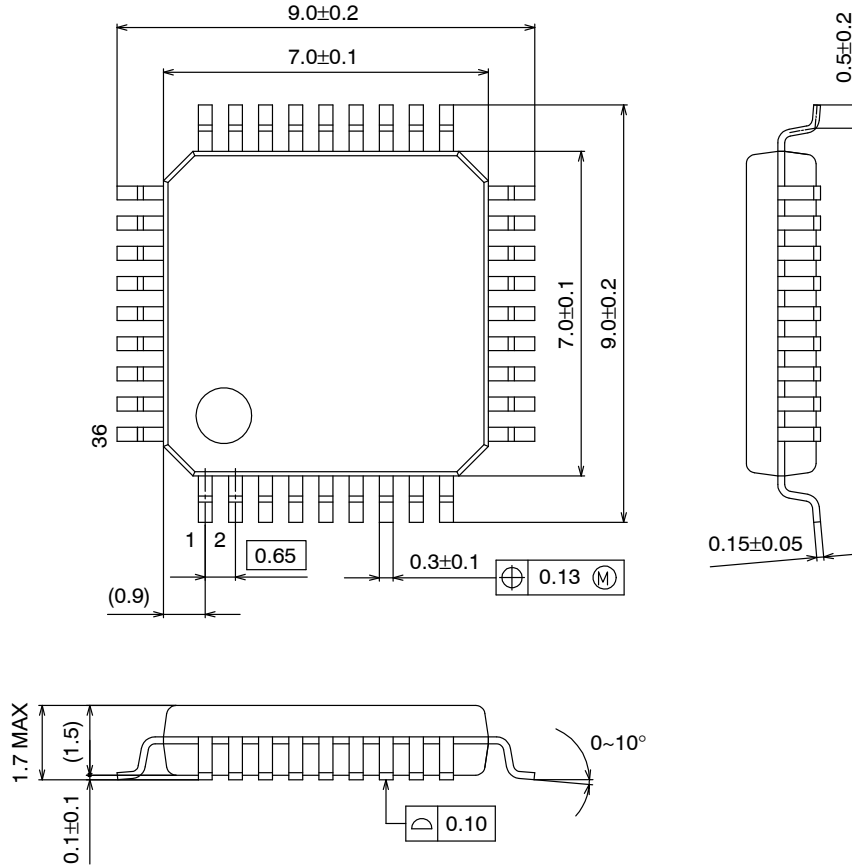


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

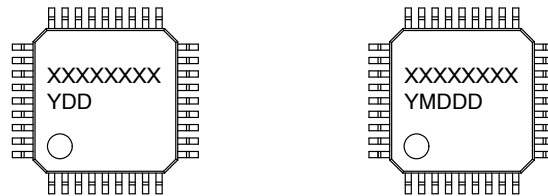


LQFP36 7x7 / QFP36
CASE 561AV
ISSUE A

DATE 31 OCT 2013



GENERIC MARKING DIAGRAM*



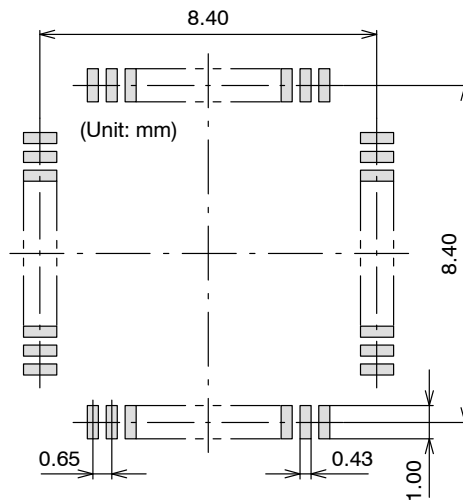
XXXXX = Specific Device Code
 Y = Year
 DD = Additional Traceability Data

XXXXX = Specific Device Code
 Y = Year
 M = Month
 DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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SOLDERING FOOTPRINT*



NOTE: The measurements are not to guarantee but for reference only.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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